

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
General Description

The SRE50N120FSUDA is a Field Stop Trench IGBT with anti-parallel diode, which offers low switching losses, high energy efficiency and high avalanche ruggedness for soft switching applications such as UPS, solar inverters, etc. The SRE50N120FSUDA is available in TO-247 and TO-247Plus packages.

Features

- High Breakdown Voltage to 1200V
- Advanced Trench Fieldstop technology
 - Low $V_{CE(sat)}$
 - High Ruggedness, Temperature Stability
 - Easy Parallel Switching Capability due to Positive Temperature Coefficient in $V_{CE(SAT)}$
- Soft Current Turn-off Waveforms
- Non-Automotive Qualified

Application

- Solar Inverters
- Uninterrupted Power Supply
- Industrial Power Supplies
- Grid Inverter

Ordering Information

SRE50N120FSUDA□□-□

Circuit Type _____
 Package _____
 T: TO-247 TP:TO-247Plus

G: Green
 Blank: Tube
 TR: Tape & Reel

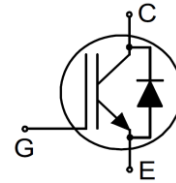
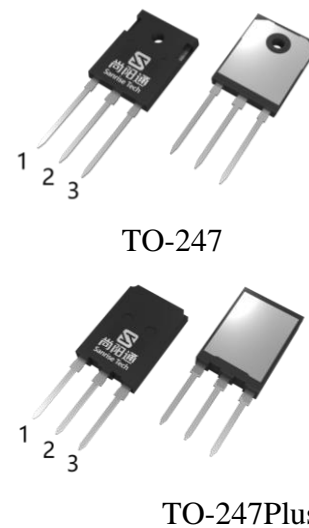
Symbol


Figure 1 Symbol of SRE50N120FSUDA

Package Type


Pin 1- Gate; Pin 2&backside- Collector; Pin 3-Emitter

Figure 2 Package Type of SRE50N120FSUDA

Package	Part Number	Marking ID	Packing Type
TO-247	SRE50N120FSUDAT-G	SRE50N120FSUDATG	Tube
TO-247Plus	SRE50N120FSUDATP-G	SRE50N120FSUDATPG	Tube

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Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Collector-emitter voltage		V_{CES}	1200	V
Gate-emitter Voltage		V_{GES}	± 20	V
Transient Gate-emitter Voltage			± 30	V
Continuous Collector Current	$T_C=25^\circ\text{C}$	I_C	100	A
	$T_C=100^\circ\text{C}$		50	
Pulsed Collector Current, Limited by T_{Jmax}		I_{CM}	200	A
Diode Continuous Collector Current ($T_C=100^\circ\text{C}$)		I_F	50	A
Diode Pulsed Current, Limited by T_{Jmax}		I_{FM}	270	A
Power dissipation (TO-247)	$T_C=25^\circ\text{C}$	P_{tot}	500	W
	$T_C=100^\circ\text{C}$		250	W
Power dissipation (TO-247Plus)	$T_C=25^\circ\text{C}$	P_{tot}	650	W
	$T_C=100^\circ\text{C}$		325	W
Maximum Operating Junction Temperature		T_{Jmax}	175 ⁽¹⁾	$^\circ\text{C}$
Storage Temperature		T_{STG}	-55 ~ 150	$^\circ\text{C}$
Lead Temperature (Soldering, 10 sec)		T_{LEAD}	260	$^\circ\text{C}$

Note:

 1. Reliability testing conducted at $T_j=175^\circ\text{C}$.

Thermal Resistance

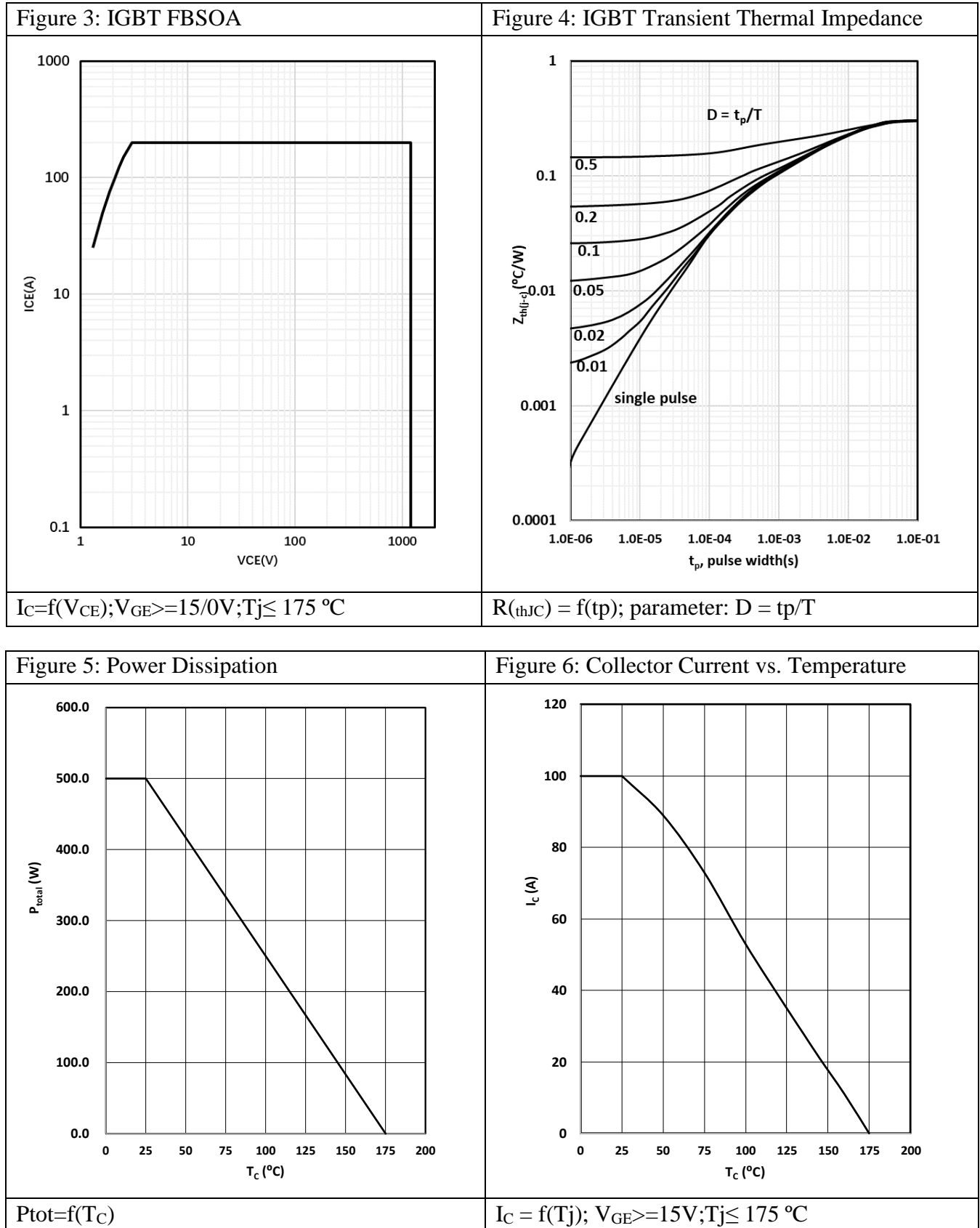
Parameter	Package	Symbol	Min	Typ	Max	Unit
IGBT thermal Resistance, Junction-to-Case	TO-247	R_{thJC}	-	-	0.3	$^\circ\text{C}/\text{W}$
Diode thermal Resistance, Junction-to-Case	TO-247	R_{thJC}	-	-	0.6	
IGBT thermal Resistance, Junction-to-Case	TO-247Plus	R_{thJC}	-	-	0.23	
Diode thermal Resistance, Junction-to-Case	TO-247Plus	R_{thJC}	-	-	0.5	
Thermal Resistance, Junction-to-Ambient	TO-247 TO-247Plus	R_{thJA}	-	-	40	

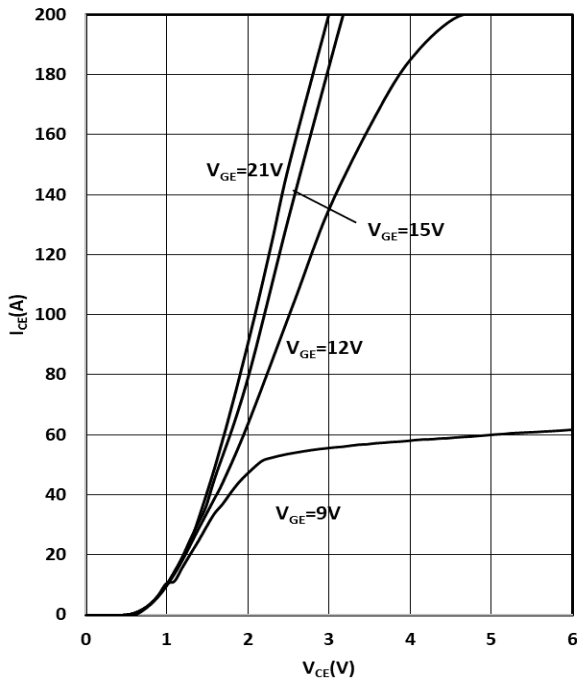
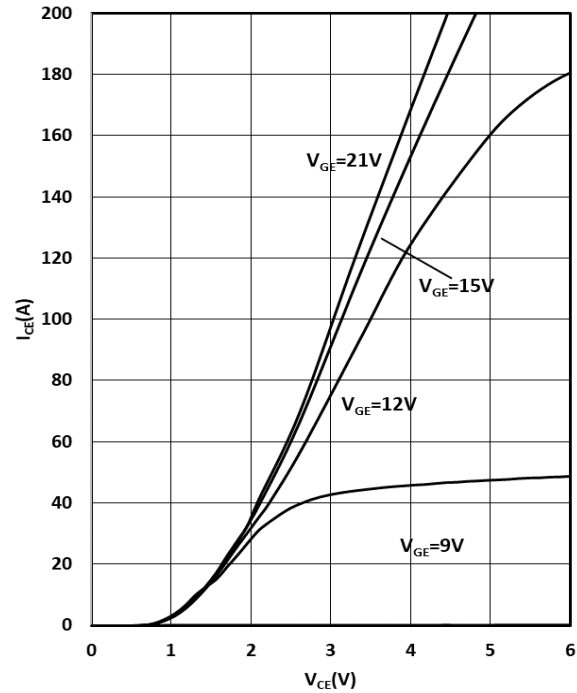
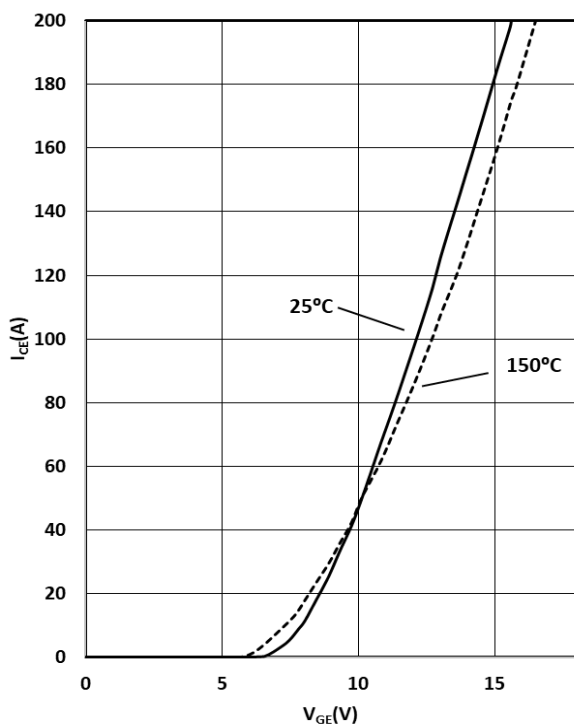
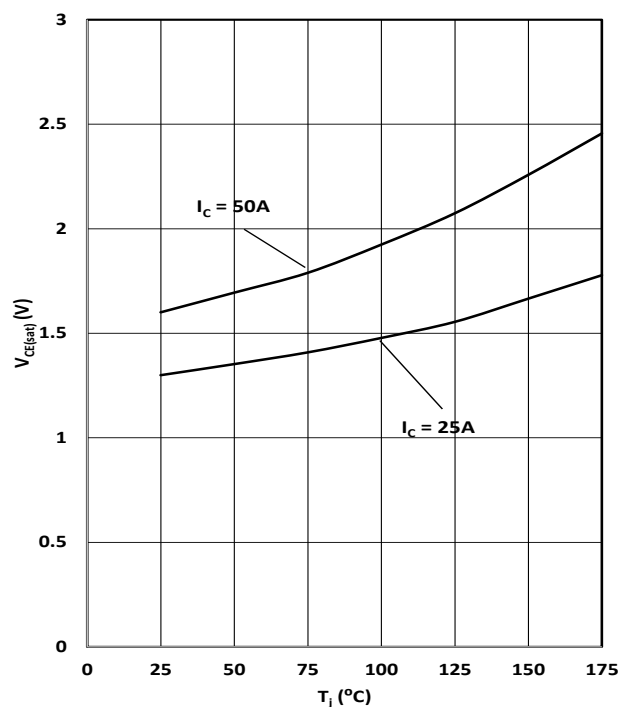
50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Electrical Characteristics
 $T_J = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit	
Statistic Characteristics							
Collector-emitter Breakdown Voltage	BV_{CES}	$V_{GE}=0V, I_C=250\mu A$	1200			V	
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}, I_C=1.6mA$	4.6	5.4	6.2	V	
Collector-emitter saturation voltage	V_{CEsat}	$V_{GE}=15V, I_C=50A,$ $T_J=25^\circ\text{C}$		1.6	2.0	V	
		$T_J=125^\circ\text{C}$		2.0		V	
		$T_J=175^\circ\text{C}$		2.43		V	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE}=1200V, V_{GE}=0V$ $T_J=25^\circ\text{C}$			100	μA	
		$T_J=175^\circ\text{C}$			1	mA	
Gate-emitter Leakage Current	Forward	I_{GESF}	$V_{GE}=20V, V_{CE}=0V$			100	nA
	Reverse	I_{GESR}	$V_{GE}=-20V, V_{CE}=0V$			-100	nA
Dynamic Characteristics							
Input Capacitance	C_{IES}	$V_{CE}=25V, V_{GE}=0V,$ $f=1MHz$		4450		pF	
Output Capacitance	C_{OES}			215			
Reverse Transfer Capacitance	C_{RES}			26			
Gate Resistance	R_G	$f=1MHz, \text{Open Drain}$		1.2		Ω	
Turn-on Delay Time	$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{CC}=600V, I_C=50A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		44		ns	
Rise Time	t_r			55		ns	
Turn-off Delay Time	$t_{d(off)}$			164		ns	
Fall Time	t_f			127		ns	
Turn-on energy	E_{on}			3.4		mJ	
Turn-off energy	E_{off}			1.6		mJ	
Total switching energy	E_{ts}			5.0		mJ	
Turn-on Delay Time	$t_{d(on)}$		$T_J=150^\circ\text{C}$ $V_{CC}=600V, I_C=50A$ $R_G=10\Omega, V_{GE}=0/15V$ Energy losses include "tail" and diode reverse recovery		60.4		ns
Rise Time	t_r				46.4		ns
Turn-off Delay Time	$t_{d(off)}$				302		ns
Fall Time	t_f				196		ns
Turn-on energy	E_{on}				4.3		mJ
Turn-off energy	E_{off}				2.1		mJ
Total switching energy	E_{ts}				6.4		mJ
Gate to Emitter Charge	Q_{GE}	$V_{CC}=600V, I_C=50A$ $V_{GE}=0 \text{ to } 15V$			62		nC
Gate to Collector Charge	Q_{GC}				170		
Gate Charge Total	Q_G				410		

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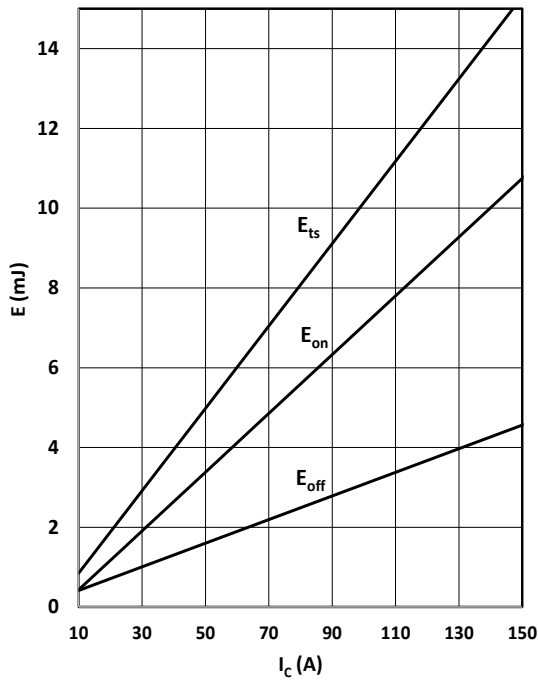
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Diode Characteristics						
Diode Forward Voltage	V_F	$I_F=25A$ $T_j=25^\circ C$		1.71	2.1	V
		$I_F=25A$ $T_j=100^\circ C$		1.54		
		$I_F=25A$ $T_j=175^\circ C$		1.39		
		$I_F=50A$ $T_j=25^\circ C$		2.05	2.45	
		$I_F=50A$ $T_j=100^\circ C$		1.87		
		$I_F=50A$ $T_j=175^\circ C$		1.72		
Reverse Recovery Time	t_{rr}	$T_j=25^\circ C$ $V_R=600V, I_F=50A$ $dI_F/dt=1200A/us$		130		ns
Reverse Recovery Charge	Q_{rr}			2.47		μC
Peak Reverse Recovery Current	I_{rrm}			38		A
Diode peak rate of fall of reverse Recovery current during t_b	di_{rr}/dt			-622		A/us
Reverse Recovery Time	t_{rr}	$T_j=100^\circ C$ $V_R=600V, I_F=50A$ $dI_F/dt=1200A/us$		204		ns
Reverse Recovery Charge	Q_{rr}			5.18		μC
Peak Reverse Recovery Current	I_{rrm}			56		A
Diode peak rate of fall of reverse Recovery current during t_b	di_{rr}/dt			-648		A/us
Reverse Recovery Time	t_{rr}	$T_j=150^\circ C$ $V_R=600V, I_F=50A$ $dI_F/dt=1200A/us$		258		ns
Reverse Recovery Charge	Q_{rr}			7.88		μC
Peak Reverse Recovery Current	I_{rrm}			69		A
Diode peak rate of fall of reverse Recovery current during t_b	di_{rr}/dt			-704		A/us

50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Typical Performance Characteristics


50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Figure 7: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 8: Typical Output Characteristics

 $I_C = f(V_{CE}); T_j = 175^\circ\text{C}; \text{parameter: } V_{GE}$
Figure 9: Typical transfer characteristic

 $I_C = f(V_{GE}); V_{CE} = 20\text{V}$
Figure 10: Typical collector-emitter saturation voltage as a function of junction temperature

 $V_{CE} = f(T_j); V_{GE} = 15\text{V}$

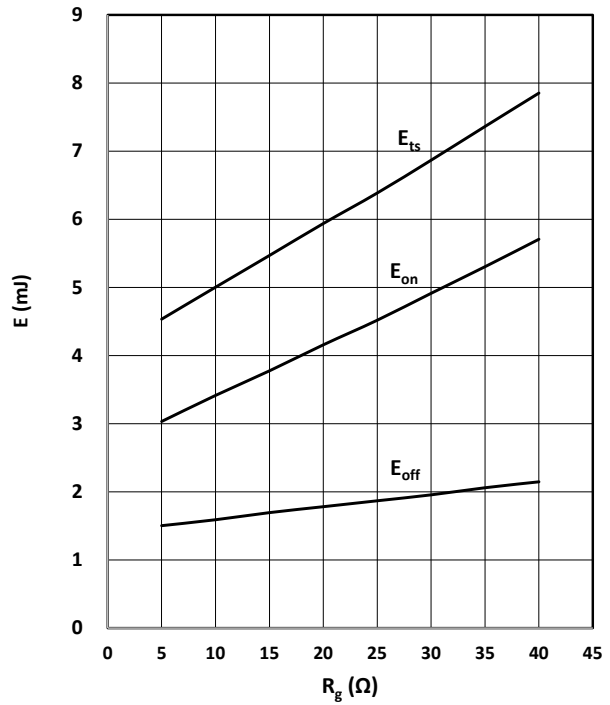
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Figure 11: Typical switching energy losses as a function of collector current



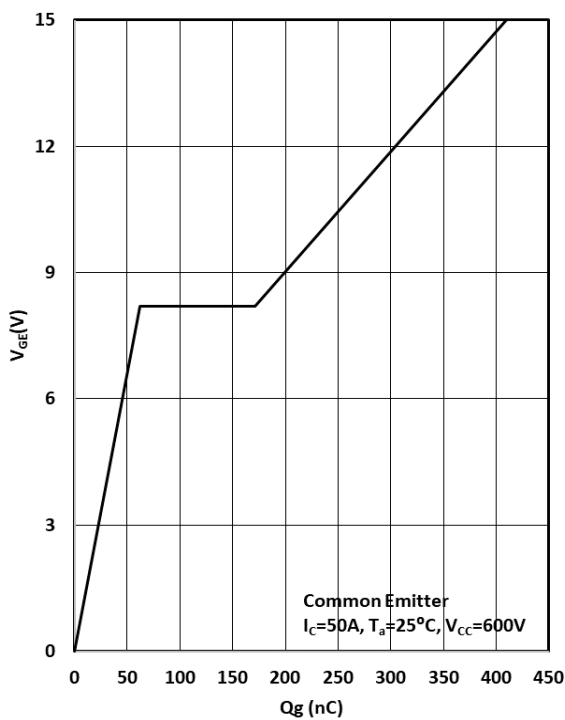
$$E=f(I_C) ; V_{CE}=600V; T_j=25^{\circ}C; R_G=10\Omega$$

Figure 12: Typical switching energy losses as a function of gate resistor



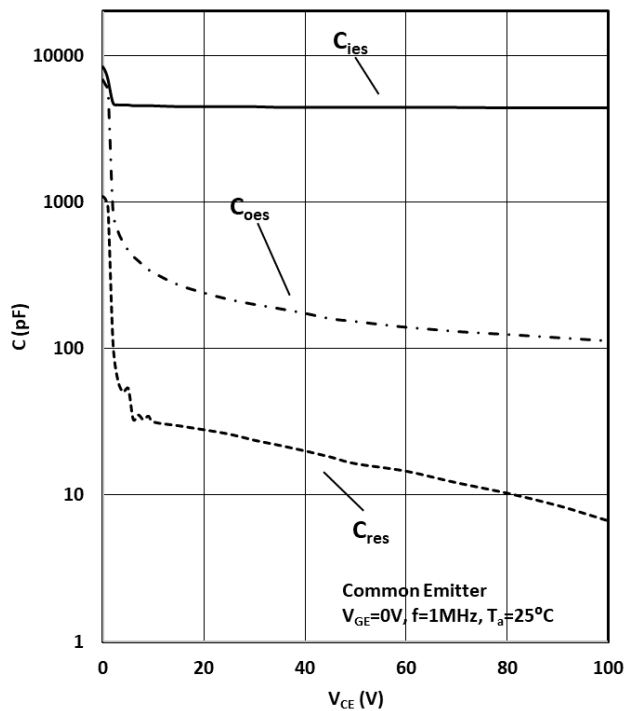
$$E=f(R_G) ; V_{CE}=600V; T_j=25^{\circ}C; I_C=50A$$

Figure 13: Typical Gate Charge



$$V_{GE}=f(Q_g), I_C=50A$$

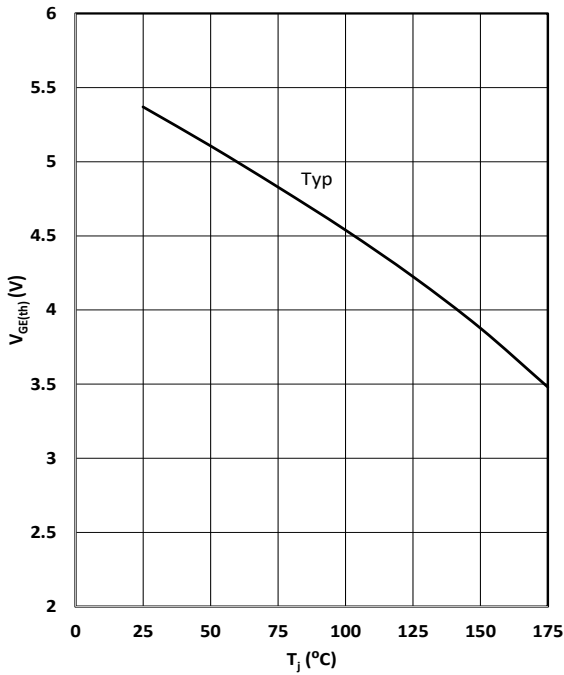
Figure 14: Typical Capacitances



$$C=f(V_{CE}); V_{GE}=0; f=1MHz$$

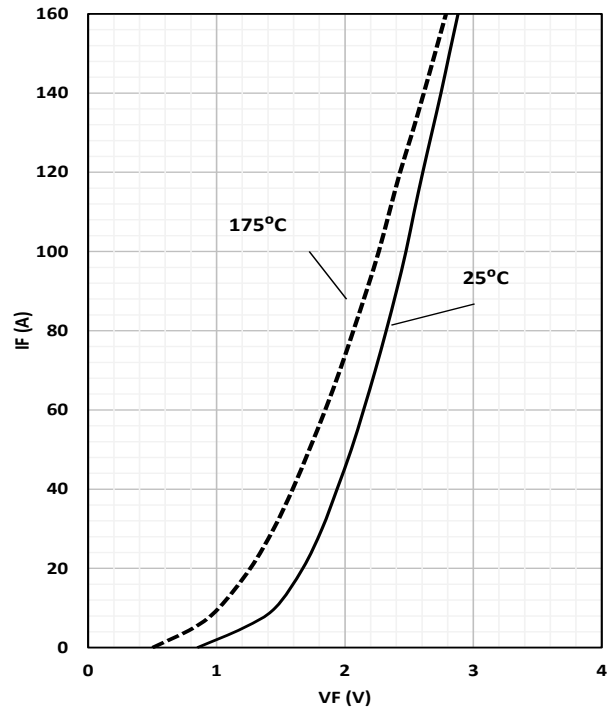
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Figure 15: Gate-emitter threshold voltage as a function of junction temperature



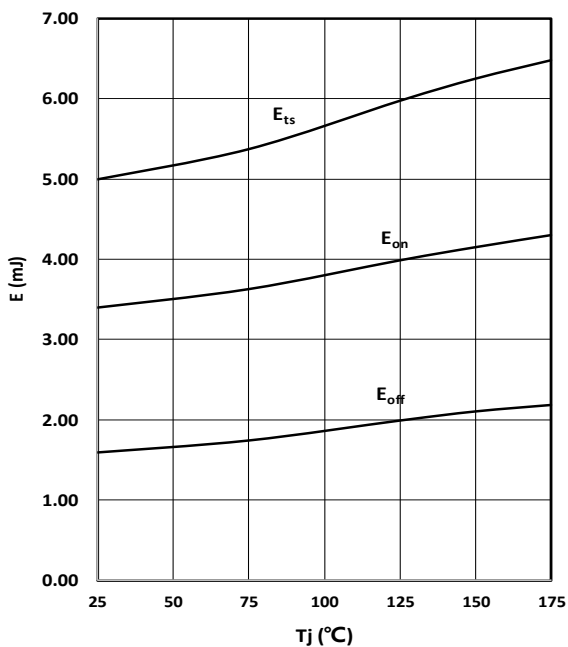
$$V_{GE} = f(T_j); I_{CE} = 1.6 \text{ mA}$$

Figure 16: Typical diode forward current as a function of forward voltage

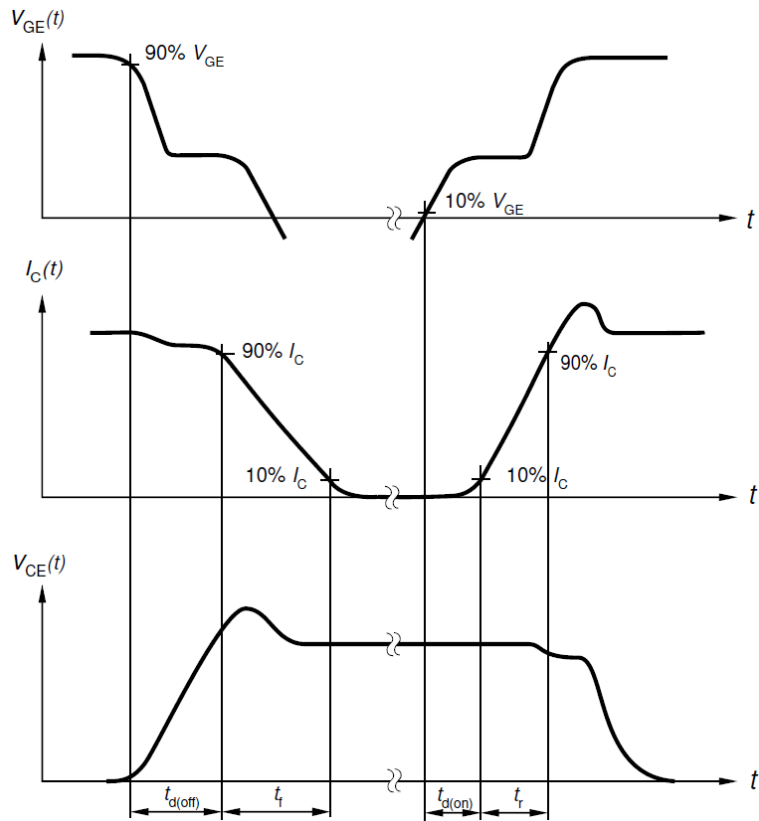
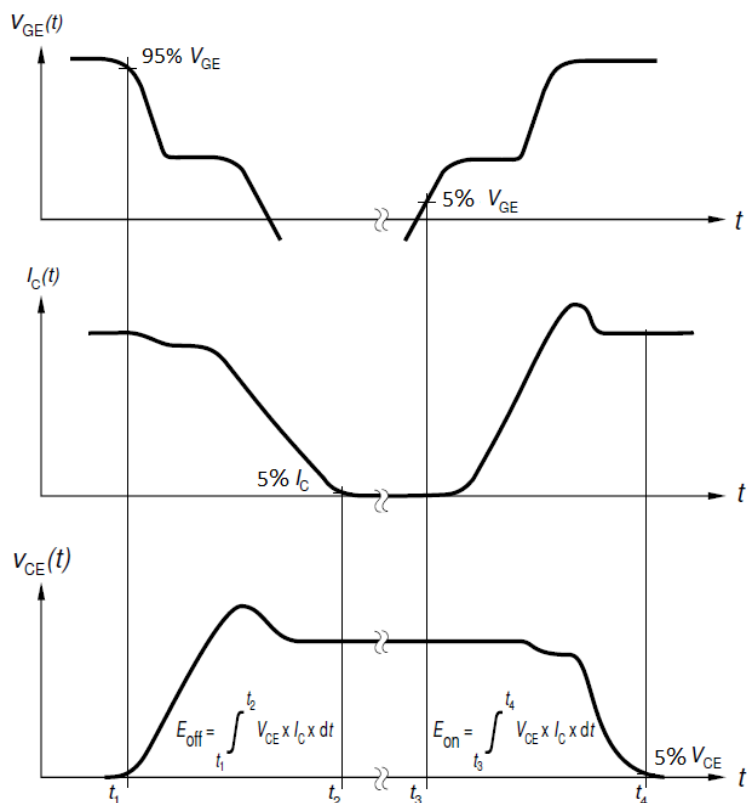


$$V_F = f(I_F)$$

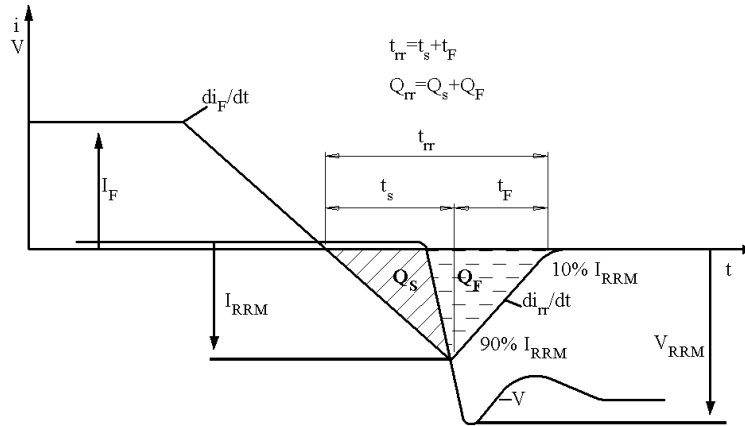
Figure 17: Typical switching energy losses as a function of junction temperature



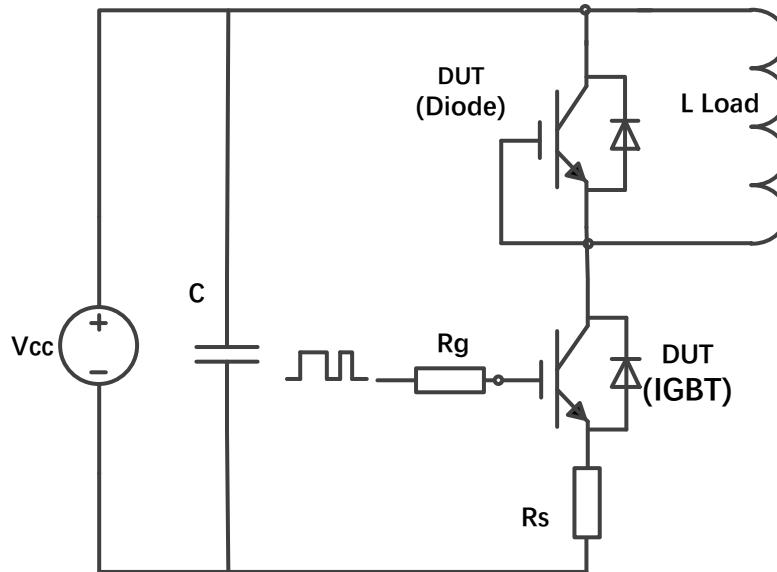
$$E = f(T_j); V_{CE} = 600 \text{ V}; I_C = 50 \text{ A}; R_G = 10 \Omega$$

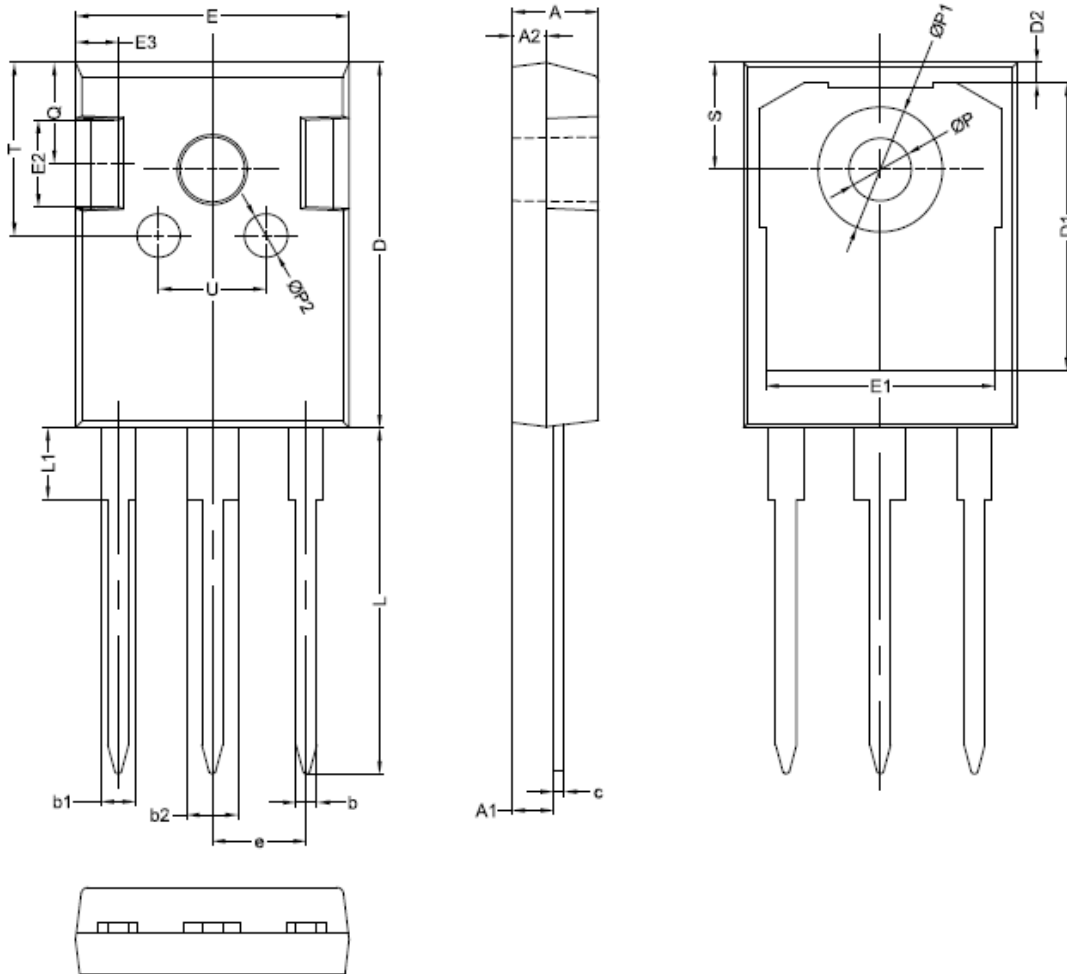
Test Circuits
1. Definition Switching times

2. Definition Switching losses


3. Definition Diode Switching Characteristics



4. Dynamic test circuit



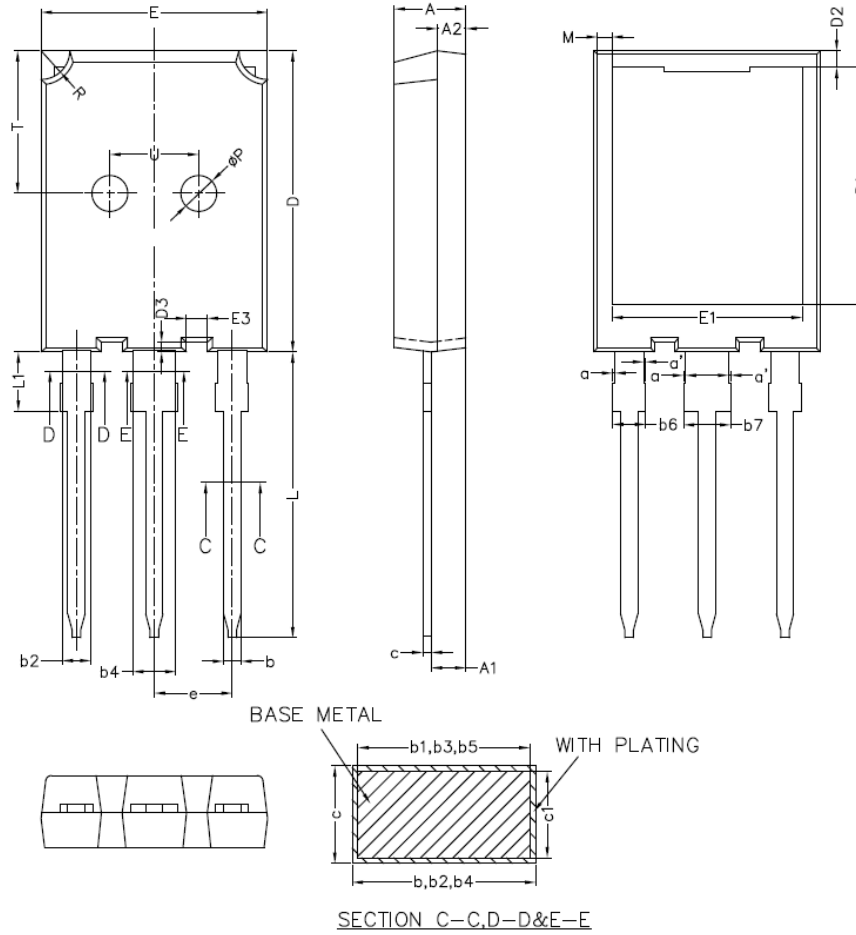
Mechanical Dimensions
TO-247
Unit: mm


Symbol	Dimensions(mm)			Symbol	Dimensions(mm)		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	4.80	5.00	5.20	E2	-	5.00	-
A1	2.21	2.41	2.61	E3	-	2.50	-
A2	1.90	2.00	2.10	e	5.44(BSC)		
b	1.10	1.20	1.35	L	19.42	19.92	20.42
b1	-	2.00	-	L1	-	4.13	-
b2	-	3.00	-	P	3.50	3.60	3.70
c	0.55	0.60	0.75	P1	-	-	7.40
D	20.80	21.00	21.20	P2	-	2.50	-
D1	-	16.55	-	Q	-	5.80	-
D2	-	1.20	-	S	6.05	6.15	6.25
E	15.60	15.80	16.00	T	-	10.00	-
E1	-	13.30	-	U	-	6.20	-

Mechanical Dimensions

TO-247Plus

Unit: mm



50A 1200V Trench Fieldstop IGBT with anti-parallel diode SRE50N120FSUDA
Mechanical Dimensions

Symbol	Dimensions(mm)		
	Min.	Typ.	Max.
A	4.90	5.00	5.10
A1	2.31	2.41	2.51
A2	1.90	2.00	2.10
α	0	-	0.15
α'	0	-	0.15
b	1.16	-	1.26
b1	1.15	1.2	1.22
b2	1.96	-	2.06
b3	1.95	2.00	2.02
b4	2.96	-	3.06
b5	2.95	3.00	3.02
b6	-	-	2.25
b7	-	-	3.25
c	0.59	-	0.66
c1	0.58	0.60	0.62
D	20.90	21.00	21.10
D1	16.25	16.55	16.85
D2	1.05	1.17	1.35
D3	0.58	0.68	0.78
E	15.70	15.80	15.90
E1	13.10	13.26	13.50
E3	1.35	1.45	1.55
e	5.34	5.44	5.54
L	19.80	19.92	20.10
L1	3.90	-	4.30
M	0.70	-	1.30
P	2.40	2.50	2.60
R	1.90	2.00	2.10
T	9.80	-	10.20
U	6.00	-	6.40



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